



Product Brief

SLE 97 SOLID FLASH™ Family

High Performance for your NFC SIM Card

The SLE 97 SOLID FLASH™ Family is the Infineon's state-of-the-art 32-bit product generation, for high performance security chip cards. It comes in various form factors, addressing besides SIM/UICC NFC secure elements also embedded secure elements.

25% More Performance than Standard SC300™ Products

The SLE 97 products are the first products to benefit from the collaboration between Infineon and ARM® in the field of controllers for chipcard and security applications. They implement a unique 32-bit CPU based on the ARM® SecurCore™ SC300™ enhanced by Infineon's cache and security technology.

1.5MB Storage for your NFC SIM/UICC

Thanks to the code density offered by the ARM® architecture, it provides easily more than 1MB for the NFC applications, and supports in long term the wide deployment of NFC in the market field.

Available in Mini-SIM and Micro-SIM

With their optimized footprint, the SLE 97 products are able to support smallest SIM form factors, such as 3FF and 4FF, using the Infineon's FlipChip Technology (FCOS™).

Applications

- NFC SIM/UICC
- Embedded SIM with NFC support
- USB SIM cards with NFC support
- CIPURSE™ for mobile



NFC-Tuned Features

- ARM® SecurCore™ SC300™ enhanced by Infineon's cache and security technology
- Up to 1.5MB SOLID FLASH™ allowing fast prototyping and short time-to-market
- Very high endurance NVM (500K) for best quality products
- Crypto processor for RSA and elliptic curves calculations
- Crypto processor for AES, (3)DES calculations
- True random number generator
- ISO 7816 up to 1.25MBaud
- Inter-chip / full speed USB up to 12Mbit/s

NFC-Tuned Features

- Single Wire Protocol (SWP) interface up to 1.7Mbit/s
- Mifare compatible interface
- CIPURSE™
- NFC battery-off mode

Certification

- CC EAL 5+ high
- EMVCo

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Product Table Summary

Sales Code	SOLID FLASH™ [kB]	Interfaces	Typical Applications
SLE 97CNFX1M50PE	1544	ISO 7816, SWP	NFC SIM/UICC
SLE 97CNFX1M30PE	1280		
SLE 97CNFX1M00PE	1024		
SLE 97CNFX8000PE	800		
SLE 97CUNFX1M50PE	1544	ISO 7816, SWP, USB	
SLE 97CUNFX1M30PE	1280		
SLE 97CUNFX1M00PE	1024		
SLE 97CUNFX8000PE	800		

Available in wafer, bare die, flip chip and wire bonded modules.



Wafer (Die)



M4.8



MFC5.8



MFC5.4/MFC5.6



MFC1.6

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